

===== WPI =====

- TI - Sealing of joint of glass plate and frame with no displacement of glass plate - using one-liq. normal temp. and humidity curable compsn. contg. PVC or metal methacrylate, plasticiser, organo-silicon cpd. and filler
- AB - J06073955 A one-liq. normal temp. humidity curable compsn. is applied to the joint of the glass plate and frame with the compsn. heated and liquefied.
- The compsn. pref. contains powdered organic high polymer cpd., a liq. dissolving swelling agent for dissolving the cpd. by heating, a room temp. humidity curable organic silicon cpd. and a filler. The organic high polymer cpd. comprises a polyvinyl chloride resin or methyl methacrylate resin. The dissolving swelling agent comprises a plasticiser. The room temp. humidity curable organic silicon cpd. comprises an organic silicon cpd. having at least two gps. of formula (R)n-Si-(X)3-n (I) in a mol.. In (I), X = a hydrolysing gp.; R = a gp. except the hydrolysing gp.; and n = 0-2. The filler comprises fumed silica, precipitating silica, silicic anhydride, moisture-contg. silicic acid, C black, CaCO3, MgCO3, diatomaceous earth, burned clay, clay, talc, titanium oxide, bentonite, organic bentonite, ferric oxide, silasu balloon, asbestos, glass fibre or filament.
- USE/ADVANTAGE - The method seals the joint of the glass plate and the frame including an Al sash, metal sash, wood sash, stainless steel sash or plastic sash. The method fixes the one-liq. normal temp. humidity curable compsn. to the joint in a short time e.g. 5 mins. After applying the compsn. to the joint, no glass plate is displaced even if the glass plate and the frame are moved.
- PN - JP6073955 A 19940315 DW199415 E06B3/56 005pp
- PR - JP19920228983 19920827
- PA - (SEME-N) SEMEDAIIN KK
- MC - A11-C01 A11-C02 A12-R08 G04-B02 L01-H07
- DC - A93 G04 L01 Q48
- IC - C03C27/10 ;C08K3/00 ;C08K5/54 ;C08L27/06 ;C08L33/12 ;C09D5/34 ;C09K3/10 ; E06B3/56
- AN - 1994-124495 [15]

===== PAJ =====

- TI - SEALING METHOD OF TIE-IN JOINT SECTION BETWEEN GLASS PLATE AND FRAME BODY
- AB - PURPOSE: To move a glass plate and a frame body after a short time by coating a tie-in joint section between a glass frame and the frame body with a sealing medium composed of a specific one-pack normal-temperature moisture curing type composition.
- CONSTITUTION: A tie-in joint section between a frame body such as an aluminum sash and a glass plate is coated with one-pack normal-temperature moisture curing type composition under the state, in which the composition is heated at approximately 120-140 deg.C and liquefied, and a surface is levelled by a spatula immediately after the coating. The one-pack normal-temperature curing type composition contains a pulverulent organic high-molecular compound such as polyvinyl chloride, a dissolving swelling agent as a plasticizer dissolving and swelling the compound at the time of heating, a room-temperature moisture curing organic silicone compound and fillers. An ethylene vinyl acetate copolymer resin, etc., having vinyl acetate content less than 40wt.% is compounded as required. The frame body and the glass plate are fixed mutually after a fixed short time, and can be moved immediately after the fixing.
- PN - JP6073955 A 19940315
- PD - 1994-03-15
- ABD - 19940620
- ABV - 018323
- AP - JP19920228983 19920827
- GR - M1624
- PA - CEMEDINE CO LTD
- IN - KUWATA TSUTOMU; others: 05
- I - E06B3/56 ;C03C27/10 ;C08K3/00 ;C08K5/00 ;C08K5/54 ;C08L27/06 ;C08L33/12 ; C09D5/34 ;C09K3/10

BEST AVAILABLE COPY

POWERED BY **Dialog**

Basic Patent (Number,Kind,Date): JP 6073955 A2 940315

PATENT FAMILY:

Japan (JP)

Patent (Number,Kind,Date): JP 6073955 A2 940315

SEALING METHOD OF TIE-IN JOINT SECTION BETWEEN GLASS PLATE AND FRAME
BODY (English)

Patent Assignee: CEMEDINE CO LTD

Author (Inventor): KUWATA TSUTOMU; KURIHARA AKIHIRO; MATSUO KENJI;
FUTAMURA AKIO; OKAMURA NAOMI; TSUNEMORI HITACHI

Priority (Number,Kind,Date): JP 92228983 A 920827

Applic (Number,Kind,Date): JP 92228983 A 920827

IPC: * E06B-003/56; C03C-027/10; C08K-003/00; C08K-005/00; C08K-005/54; C08L-027/06;
C08L-033/12; C09D-005/34; C09K-003/10

CA Abstract No: ; 120(26)329570Y

Derwent WPI Acc No: ; C 94-124495

JAPIO Reference No: ; 180323M000132

Language of Document: Japanese

INPADOC/Family and Legal Status

© 2002 European Patent Office. All rights reserved.

Dialog® File Number 345 Accession Number 11681278

BEST AVAILABLE COPY

POWERED BY **Dialog**

SEALING METHOD OF TIE-IN JOINT SECTION BETWEEN GLASS PLATE AND FRAME BODY**Publication Number:** 06-073955 (JP 6073955 A) , March 15, 1994**Inventors:**

- KUWATA TSUTOMU
- KURIHARA AKIHIRO
- MATSUO KENJI
- FUTAMURA AKIO
- OKAMURA NAOMI
- TSUNEMORI HITACHI

Applicants

- CEMEDINE CO LTD (A Japanese Company or Corporation), JP (Japan)

Application Number: 04-228983 (JP 92228983) , August 27, 1992**International Class (IPC Edition 5):**

- E06B-003/56
- C03C-027/10
- C08K-003/00
- C08K-005/00
- C08K-005/54
- C08L-027/06
- C08L-033/12
- C08L-033/12
- C08L-033/12
- C09D-005/34
- C09K-003/10

JAPIO Class:

- 27.2 (CONSTRUCTION--- Building)
- 13.3 (INORGANIC CHEMISTRY--- Ceramics Industry)
- 13.9 (INORGANIC CHEMISTRY--- Other)
- 14.2 (ORGANIC CHEMISTRY--- High Polymer Molecular Compounds)
- 14.7 (ORGANIC CHEMISTRY--- Coating Material Adhesives)

JAPIO Keywords:

- R124 (CHEMISTRY--- Epoxy Resins)

BEST AVAILABLE COPY

Abstract:

PURPOSE: To move a glass plate and a frame body after a short time by coating a tie-in joint section between a glass frame and the frame body with a sealing medium composed of a specific one-pack normal-temperature moisture curing type composition.

CONSTITUTION: A tie-in joint section between a frame body such as an aluminum sash and a glass plate is coated with one-pack normal-temperature moisture curing type composition under the state, in which the composition is heated at approximately 120-140 deg.C and liquefied, and a surface is levelled by a spatula immediately after the coating. The one-pack normal-temperature curing type composition contains a pulverulent organic high-molecular compound such as polyvinyl chloride, a dissolving swelling agent as a plasticizer dissolving and swelling the compound at the time of heating, a room-temperature moisture curing organic silicone compound and fillers. An ethylene vinyl acetate copolymer resin, etc., having vinyl acetate content less than 40wt.% is compounded as required. The frame body and the glass plate are fixed mutually after a fixed short time, and can be moved immediately after the fixing. (From: *Patent Abstracts of Japan*, Section: M, Section No. 1624, Vol. 18, No. 323, Pg. 132, June 20, 1994)

JAPIO

© 2002 Japan Patent Information Organization. All rights reserved.

Dialog® File Number 347 Accession Number 4430055

BEST AVAILABLE COPY